

# **ECE 340: Semiconductor Electronics**

## **Chapter 5: Junctions (part IV)**

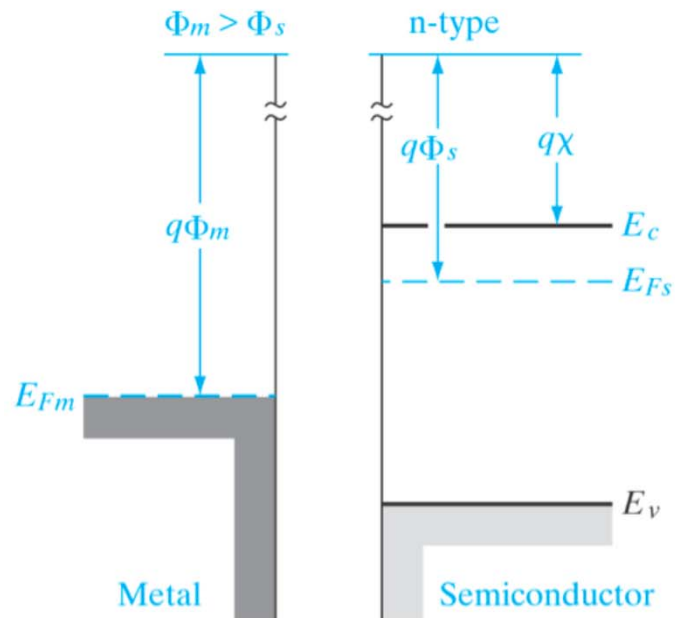
**Wenjuan Zhu**

# Outline

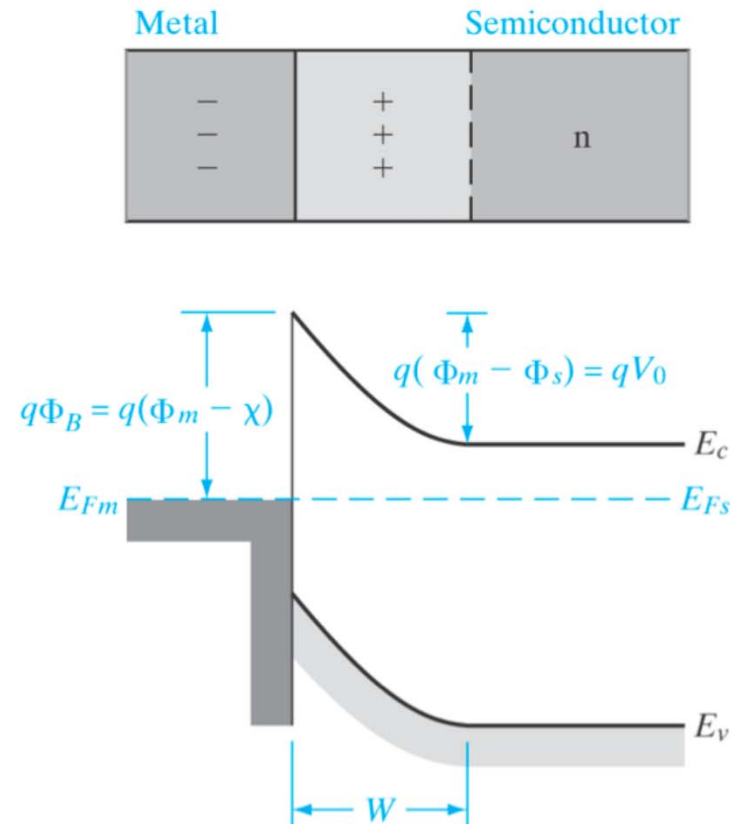
- Metal-semiconductor junction
  - Schottky barrier
  - Rectifying contacts
  - Ohmic contacts

# Schottky Barrier formation, n type semiconductor

Metal/Semiconductor Not in Contact

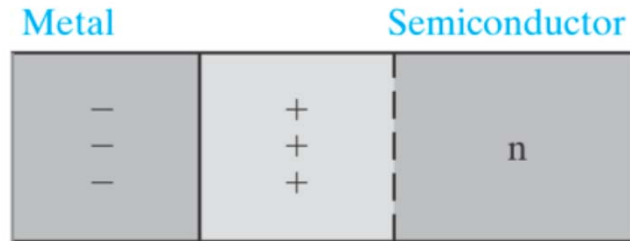


Metal/Semiconductor in Contact



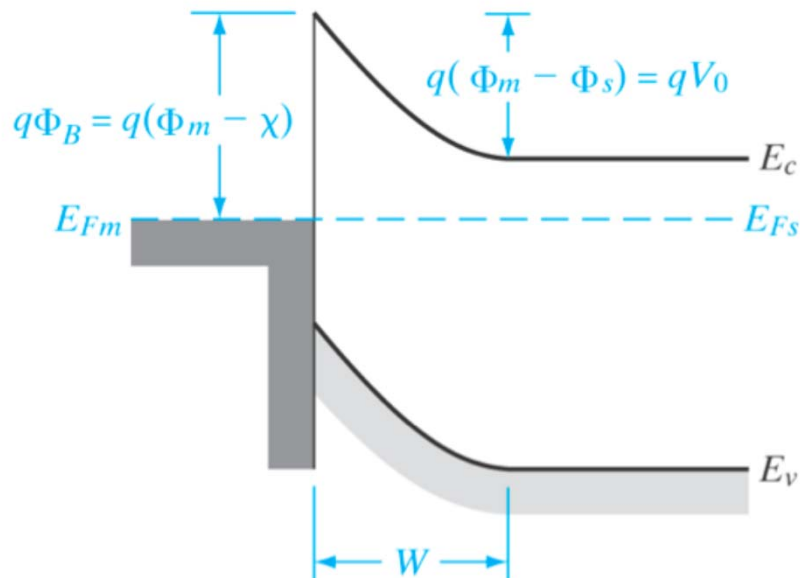
- When a metal and a semiconductor are brought together, charge transfer occurs to align the Fermi levels

# Schottky Barrier formation, n type semiconductor



**Barrier height:**  $\Phi_B = \Phi_m - X$

**Built-in voltage:**  $V_0 = \Phi_m - \Phi_s$

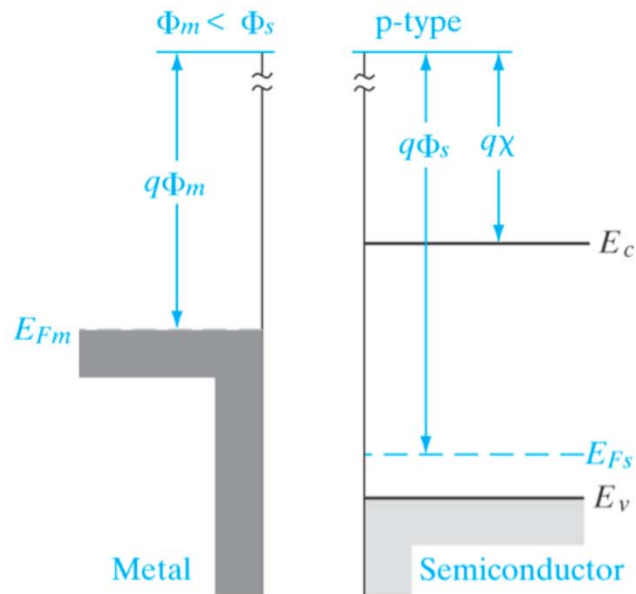


**Depletion width:**  $W = \sqrt{\frac{2\epsilon(V_0 - V_a)}{q} \frac{1}{N_d}}$

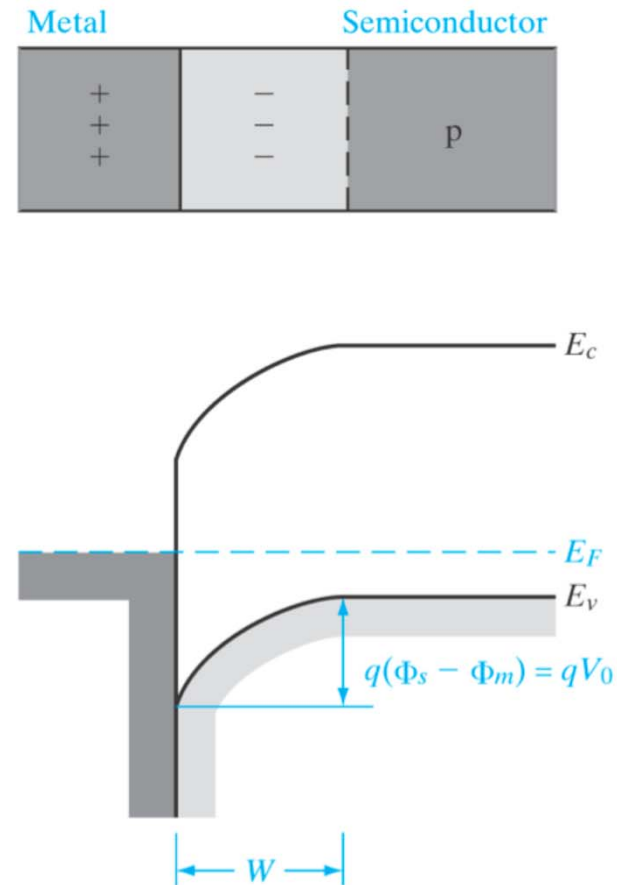
**Junction capacitance:**  $C_j = \frac{\epsilon A}{W}$

# Schottky Barrier formation, p type semiconductor

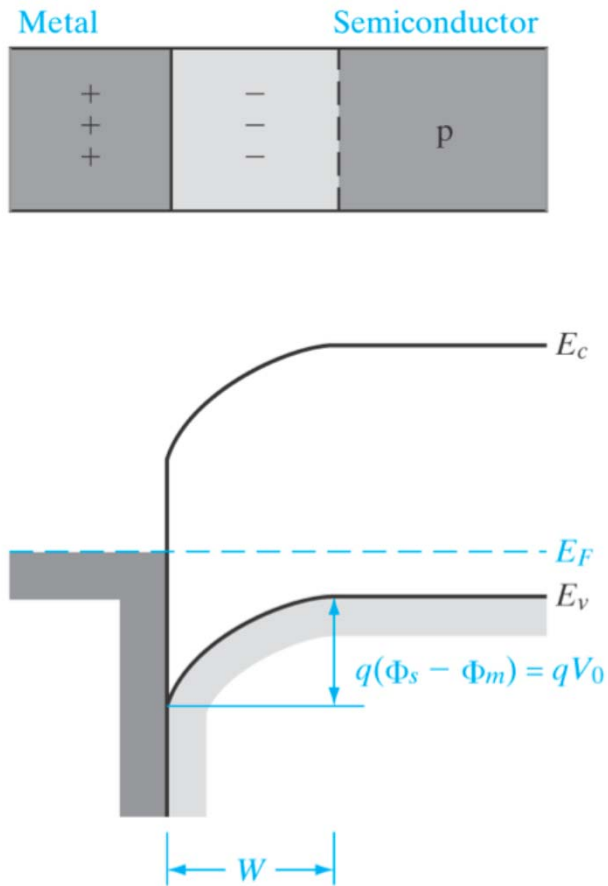
Metal/Semiconductor Not in Contact



Metal/Semiconductor in Contact



# Schottky Barrier formation, p type semiconductor

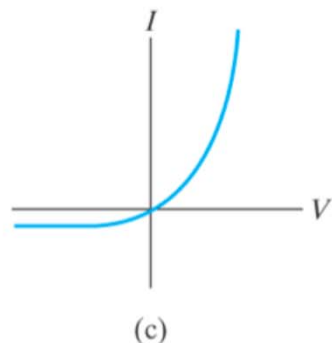
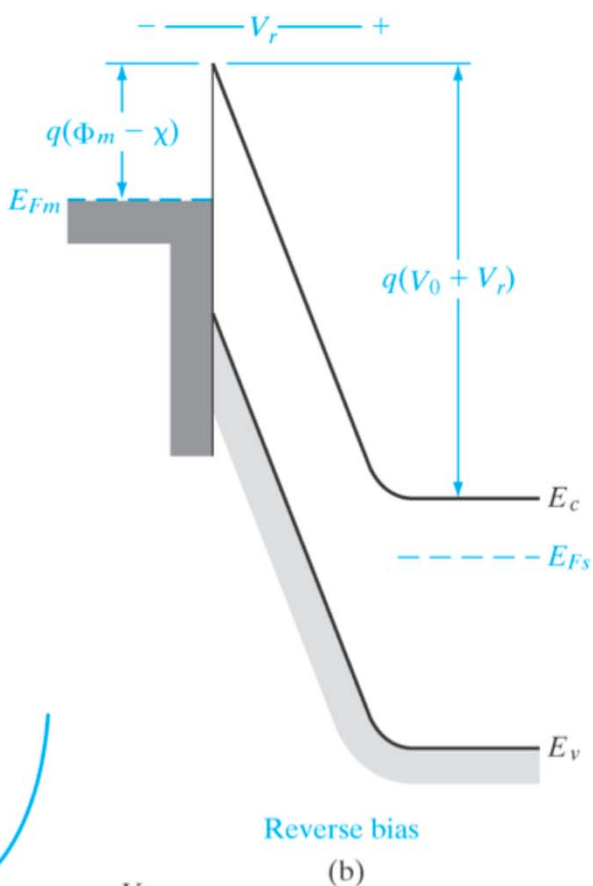
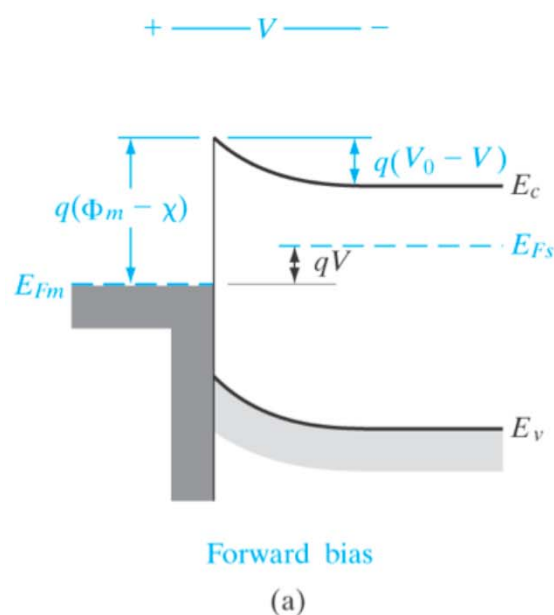


**Built-in voltage:**  $V_0 = \Phi_s - \Phi_m$

**Depletion width:**  $W = \sqrt{\frac{2\epsilon(V_0 - V_a)}{q} \frac{1}{N_a}}$

**Junction capacitance:**  $C_j = \frac{\epsilon A}{W}$

# Rectifying Contacts

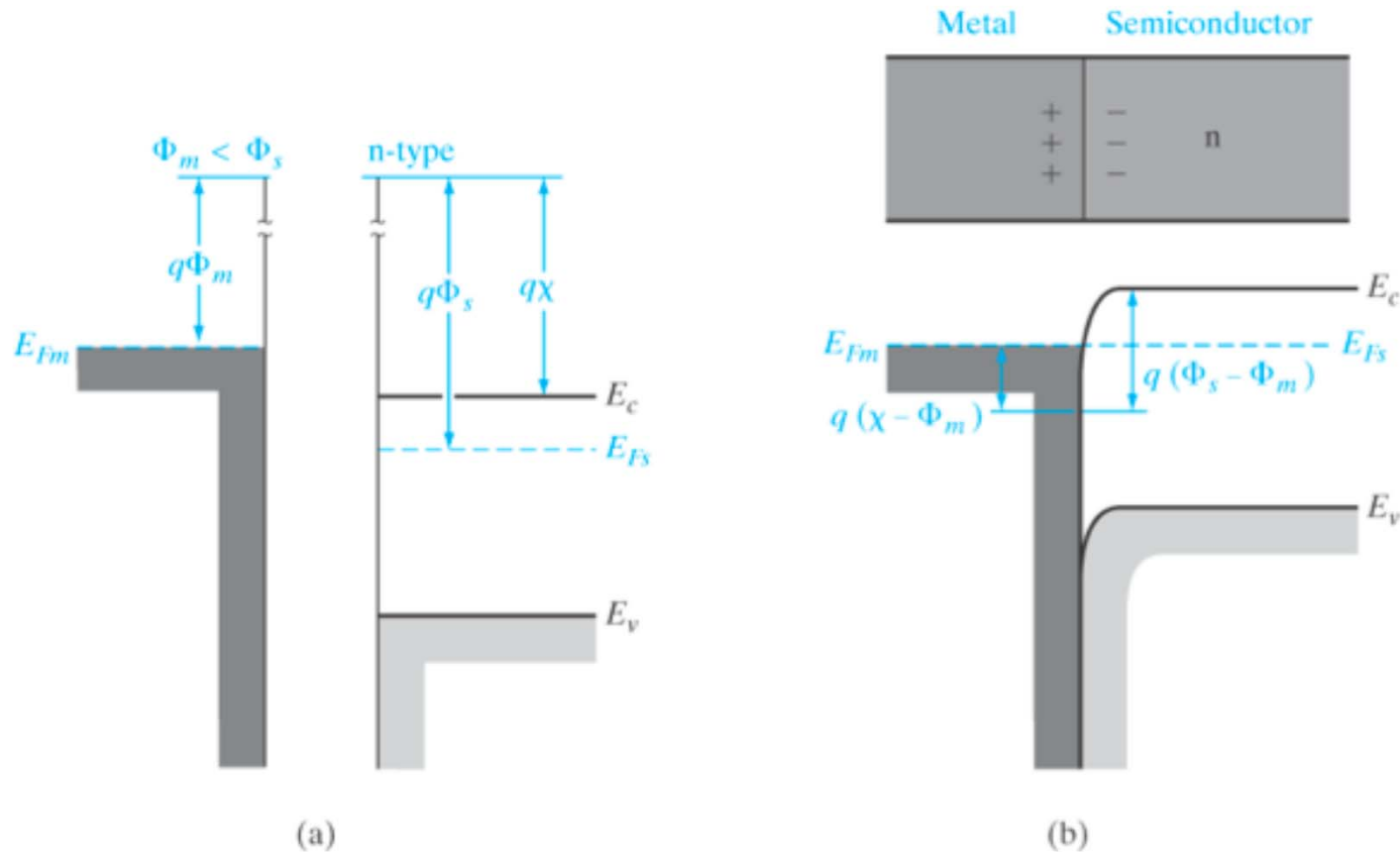


- Forward bias (negative on n side): reduce the barrier height causes majority carriers to be injected into the metal from the semiconductor.

$$I = I_0 (e^{qV/kT} - 1)$$

$$\text{where } I_0 = e^{-q\Phi_B/kT}$$

# Ohmic contact



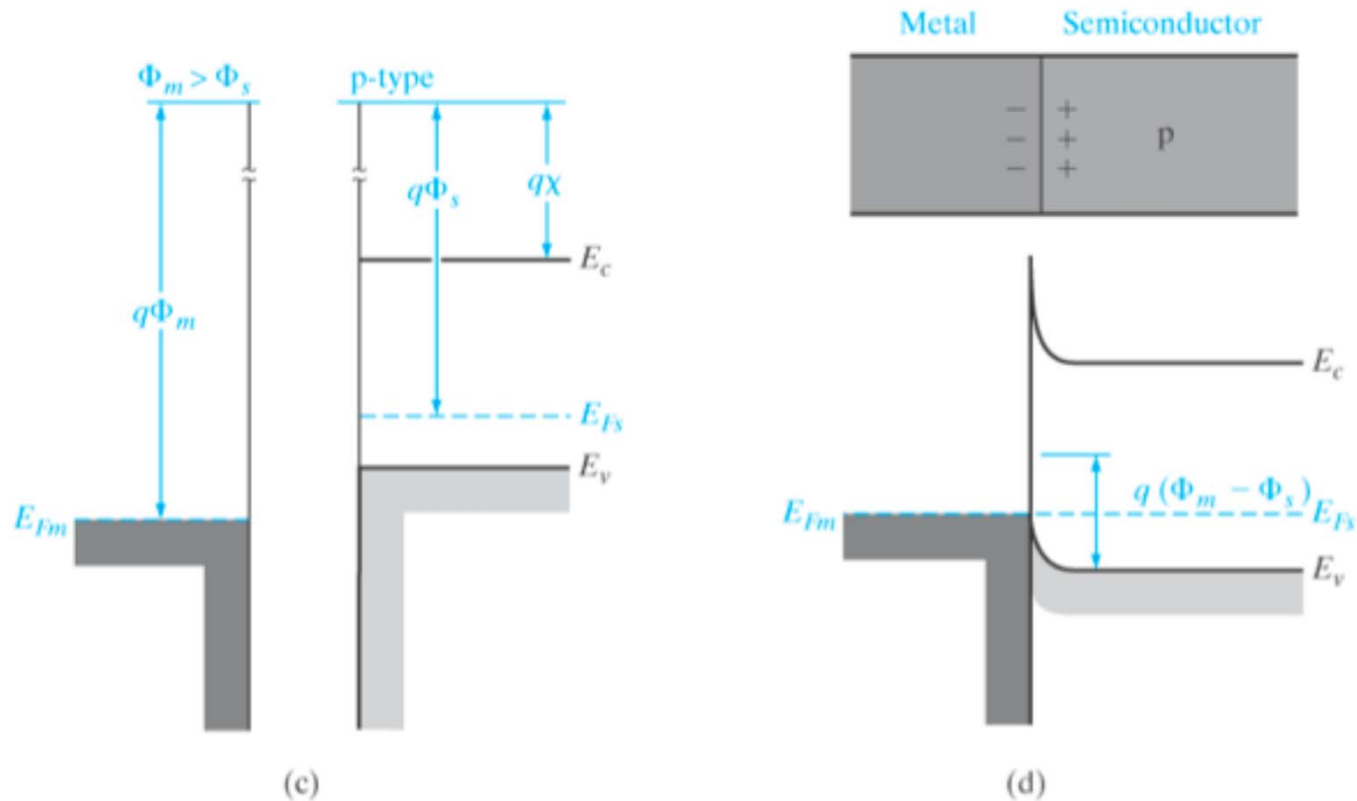
- Charge induced in the semiconductor in aligning the Fermi level is provided by majority carrier



# Contact type: doping and work function

	$\Phi_m > \Phi_s$	$\Phi_s > \Phi_m$
n-type	Rectifying	Ohmic
p-type	Ohmic	Rectifying

## Ohmic contact, another route:



- Heavily doping the semiconductor in the contact region  $\rightarrow$  depletion width is small enough for carrier to tunnel through the barrier